

# **Technical Support Bulletin**

## **Wafer Cleaving Pliers**

#52-002006



### **Product description**

The wafer cleaving pliers are designed for making clean breaks in silicon wafers, thin glass, thin quartz and similar materials. The can be used for either cleaving/breaking or nipping. These wafer cleaving pliers (also called glass running or glass breaking pliers) include two sets of jaw inserts:

- A soft set with molded ridges to facilitate a clean break over a scored line. The white indication line on the jaws enables exact positioning over the scored line
- A flat metal set for nipping a thin strip along a parallel scored line

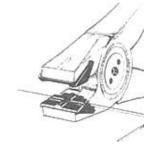
Made of lightweight, durable, strong reinforced plastic with ergonomically molded handles. Overall length is 152mm.

Always wear safely glasses and gloves when handling glass or similar material.

#### For cleaving or breaking applications.

Use the soft plastic jaw insert for cleaving or breaking out. The jaw insert with the double ridge on the jaw with the white line. The jaw insert with the single ridge in the opposite jaw.

Insert the glass, wafer approximately 10-15mm into the plier jaws. Align the center ridge under the score made in the top surface. The white line assists in making proper alignment. Squeeze gently until the material cleaves or breaks out.



#### For nipping applications.

Use the flat metal jaw inserts for this operation. Place the material flat with the score line parallel to the edge of the work surface, 1.5mm in from the edge of the work surface. Squeeze the pliers pulling towards you, out and down for a clean break.



#### Removing the jaw inserts.

To remove the jaw inserts, place a small screw driver or thin object under lower rear of the side locking tab and pry gently.

TSB 52-002006 Wafer Cleaving Pliers 2022-05-05 Revision 2



Micro to Nano Tappersweg 91 2031ET Haarlem The Netherlands T +31-85-2013155 E info@microtonano.com W www.microtonano.com Kvk AMS: # 62301959